II. AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior listings, or versions, of claims.

1. (Currently Amended) A method for generating a process aid on a wafer, the method comprising the steps of:

entering a process technology and a process aid type to be built into a program; reading technology design rules and process aid parameters for the process aid type into the program;

accessing a process aid instruction file to attain instructions for building the process aid; and

building the process aid in on the wafer using the instructions based on the technology design rules and the process aid parameters, the process aid being different than a kerf on the wafer.

- 2. (Original) The method of claim 1, wherein the building step includes building the process aid in one of a kerf and a sacrificial die on the wafer.
- 3. (Original) The method of claim 1, wherein the instructions include scheme code.
- 4. (Original) The method of claim 1, further comprising the step of documenting the process aid.
- 5. (Original) The method of claim 4, wherein the documentation includes process aid

location.

- 6. (Original) The method of claim 1, further comprising at least one of the steps of verifying the process aid against production data and testing the process aid.
- 7. (Original) The method of claim 1, further comprising the step of rerunning the step of building.
- 8. (Currently Amended) A system for generating a process aid on a wafer, the system comprising:

means for entering a process technology and a process aid type into a program; means for reading technology design rules and process aid parameters for the process aid into the program;

means for accessing a process aid instruction file to attain instructions for building the process aid; and

means for building the process aid on the wafer using the instructions based on the technology design rules and process aid parameters, the process aid being different than a kerf on the wafer.

- 9. (Original) The system of claim 8, wherein the process aid is one of an electrical device and an optical device.
- 10. (Original) The system of claim 8, wherein the instructions include scheme code.

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- 11. (Original) The system of claim 8, further comprising means for documenting the process aid.
- 12. (Original) The system of claim 11, wherein the documentation includes process aid location.
- 13. (Original) The system of claim 8, further comprising means for verifying the process aid against production data.
- 14. (Original) The system of claim 8, further comprising means for testing the process aid.
- 15. (Currently Amended) A computer program product comprising a computer useable medium having computer readable program code embodied therein for generating a process aid on a wafer, the program product comprising:

program code configured to allow entering a process technology and the process aid type;

program code configured to read technology design rules and process aid parameters for the process aid;

program code configured to access a process aid instruction file to attain instructions for building the process aid; and

program code configured to build the process aid on the wafer using the instructions based on the technology design rules and process aid parameters, the process

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aid being different than a kerf on the wafer.

- 16. (Original) The program product of claim 15, wherein the process aid is one of an electrical device and an optical device.
- 17. (Original) The program product of claim 15, wherein the instructions include scheme code.
- 18. (Original) The program product of claim 15, further comprising program code configured to document the process aid.
- 19. (Original) The program product of claim 15, further comprising program code configured to verify the process aid against production data.
- 20. (Original) The program product of claim 15, further comprising program code configured to test the process aid.

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